



# ATMEL ATF280E Rad Hard SRAM Based FPGA

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### Atmel FPGA Key Points and Architecture

ATF280E Radiation Test Results







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## **ATF280E Block-Diagram**





### **FPGA Architecture Overview**



## **Atmel Radiation Hardened FPGAs**

#### Layout rules

- Improved to avoid multiple nodes charge collection during a single heavy ion impact
- SEU hardened Memory points
  - Core cell Flip-Flops, embedded memory, configuration memory based on radiation hardened Flip-Flops
- Controller protected by classical TMR
  - Including combinatorial logic and flip-flop of all states machines
- Clock and reset trees
  - Protected by DMR (resistive isolation path based on N and P isolated path carrying the same signal)
- Your Design is radiation Hardened by construction
  - No need for SEU/SET mitigation



## **Hardened Memory Cell and Isolation Path**



## **ATF280E Key Features**

- 288K equivalent ASIC gates
- 50 MHz clock speed
- 14400 core-cells (each 2 LUT + 1 DFF)
- 115 Kbit FreeRAM (900 modules of 32x4 blocks)
- 1.8V Core / 1.8V and 3.3V Cold-sparing I/Os
- Dedicated 1.8V LVDS buffers: 8 pairs Rx + 8 pairs Tx
- 3.3V PCI-compliant I/Os
- ATC18KRHA 0.18um CMOS technology (same as ATC18RHA) ASIC and AT697F LEON2 processor)
- MCGA472 (308 + 32 User I/O) / MQFP256 (148 + 32 User I/O)
- **Configuration load integrity check**
- Configuration self-integrity check
- **Boundary scan interface**







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Application oriented SEU sensitiveness





## **ATC18RHA Radiation Performances**

ATF280 and AT697F (100MHz Leon2FT) use the same ASIC technology

- ATC18RHA, 0.18µm technology
- TID tested up to 300 Krad without parameters drift
- No SEL up to 70 MeV.cm<sup>2</sup>/mg@125°C
- SEU:
  - ATC18RHA SEU hardened DFF: LET threshold of 30 MeV/mg/cm2)
  - sensitivity of the standard DFF to SEU (LET threshold of 2 MeV/mg/cm2).
- Silicon size increase by 30% to ensure RHBD
  - To be compared to 3 to 4.5 for non RHBD



## **Test Principles**

#### Functionality and Immunity Test configurations

- Reset : configuration memory reset to low level ('0').
- Multiplier: configuration memory set to high level ('1').
- Shift register: core cell flip-flops and clock tree to upset.
- Inverted shift register: core cell flip-flops and clock tree to upset as the combinatorial path to transients.
- And chain: combinatorial path to transients.
- Free RAM: integrated FreeRAM block tested as 4K words of 16 Bits dual-port RAM.
- Free RAM with EDAC: integrated FreeRAM block tested as 4K words of 16 Bits dual-port RAM with an "Error Detector and Correction" EDAC system.

#### Test conditions

- Configuration clock frequency 1MHz
- IOs supply in the range 3V to 3.6V, nominal 3.3V
- Core voltage in the range 1.65V to 1.95V, nominal 1.8V
- Package temperature control for Latch-Up sensitivity

#### Test operator and location

- Test is run by HIREX (France)
- Test locations:
  - UCL Louvain, Belgium
  - BNL Berkeley, USA
  - RADEF Jyvaskyla, Finland





#### Single Event Latch-up

 No SEL detected over all the runs performed and in particular with the runs performed at 1.95V core voltage and 3.6V I/O buffer at LBNL with Xenon and 45 deg tilting angle that corresponds to a LET of 76 MeV/(mg/cm<sup>2</sup>) and a device under test (DUT) temperature of 125°C, up to fluence of 1.10+7 part/cm<sup>2</sup>.

#### Cross section

- The configuration SEU error cross section per device versus effective LET is derived from the tests performed in UCL, LBNL and RADEF.
  - Configuration memory SEU saturated cross-section better than 5.10-3 per device (3.10-9 cm<sup>2</sup> per bit) with a LET threshold around 30MeV at Vcc min.
  - No SET was recorded with a LET of 43 MeV/(mg/cm<sup>2</sup>).
  - SET error cross-section per device about 1.6 10-4 at 60MeV/(mg/cm<sup>2</sup>).
  - FreeRAM Asymptotic SEU error cross-section per bit about 6.5 10-8 cm<sup>2</sup>.



#### **SEU sensitivity of ATF280E configuration bits**





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#### **SEU sensitivity of ATF280E configuration bits**



- ◆ LENL1.65∨ Reset
- LENL1.77VReset
- ▲ LBNL1.65 VInverter + Register
- LENL1.95 Register 125°C
- LBNL1.65 Register
- LENL1.77 VMultiplier
- ♦ LBNL1.65∨Multiplier
- LENL1.65VAND
- UCL1.65VMultiplier
- UCL1.65VReset
- JNFL1.65VReset
- → JAFL1.65∨Shift Register
- × JNFL1.65VAnd Chain
- × JNFL1.65VFree RAM
- JNFL1.65VFree RAM EDAC
- JNFL1.65VMultiplier
- Fitted Weibull curve





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## Conclusion

#### RHBD FPGA

- ATF280
  - samples already available and designs on going
  - Improvement of power-on current (maximum in worst case conditions 1A during 10µs)
  - Application note on-going on How to design board for proven start-up current
- Multiple die package AT697F + ATF280
  - High performance AT697F (Leon2 FT SPARC V8 100MHz)
  - Peripherals in FPGA
  - One version under development under CNES contract (SPARC slave, memories controlled by FPGA)
  - One version with SPARC master to be develloped
- ATFS450 development on going using 130nm SOI process
- New architecture for 2.5Mgates RHBD SRAM based FPGA for 2012, 65nm process



